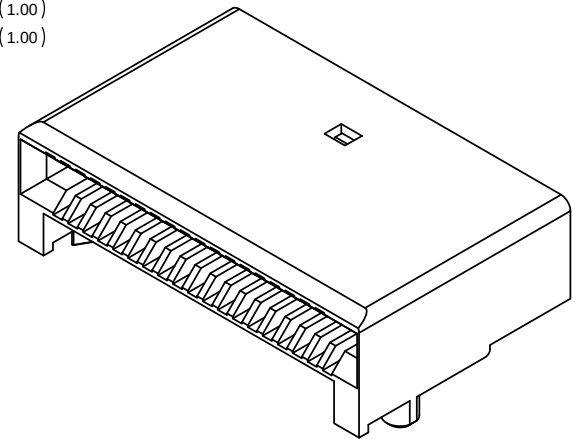
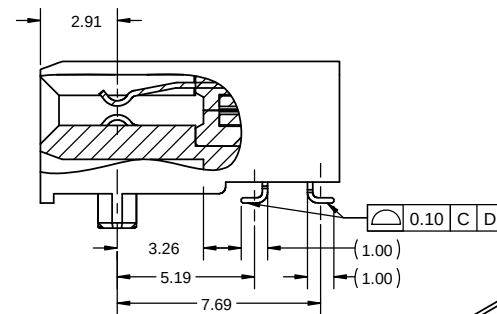
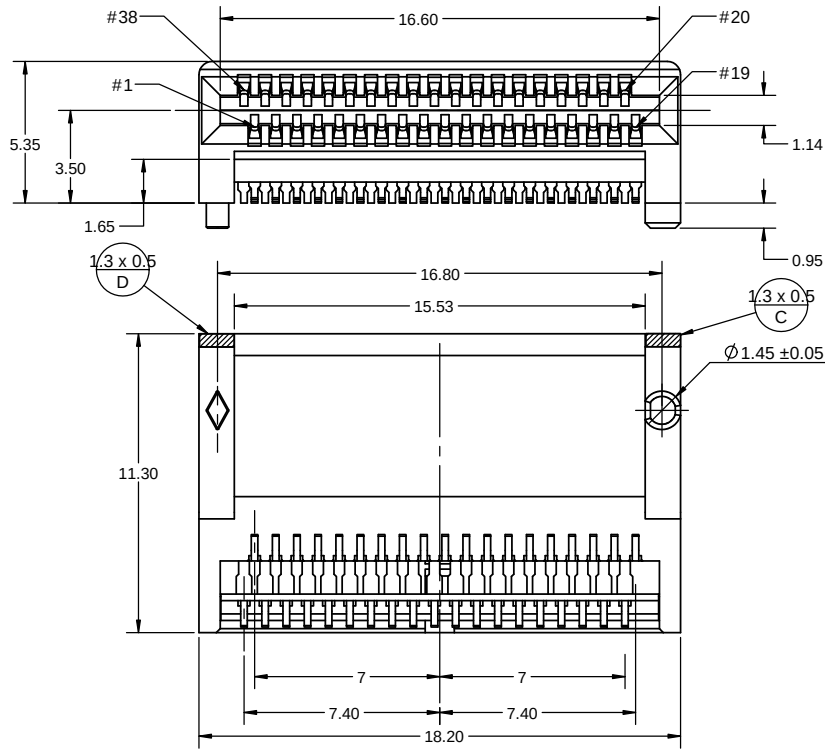




FS1 - M38 - X000 - 00

CONTACT PLATING OPTION

- 2** = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER
- 3** = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

NOTES:

1) MATERIAL:

HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER

2) ROHS COMPLIANT

KEEP-OUT ZONE IN
HATCHED AREAS
NO TRACES OR INK
MARKING ALLOWED

RECOMMENDED PCB LAYOUT
FOR FS1-M38-XXXX-XX

UNLESS SPECIFIED OTHERWISE		DRAWN	YANG J	AUG28/14	Amphenol High Speed Interconnects A Division of Amphenol Corp. www.amphenolcanada.com	
PRIMARY UNITS	MILLIMETERS	CHECKED	Checked	MON DAY#/YR		
SECONDARY	INCHES	M.E. APP'D	AC	MON DAY#/YR	eQSFP 4X28 CONNECTOR ASSEMBLY	
REFERENCE IN PARENTHESES		Q.A. APP'D	AG	MON DAY#/YR		
GENERAL TOLERANCES		DWG APP'D	DWG APP'D	MON DAY#/YR	P-FS1-M38-X000-00	
1 DECIMAL PLACE	±0.15	ENG. REL. NO.	ECN EXXXXX			
2 DECIMAL PLACES	±0.10	REF.			CODE ID NO. 03554 DWG SIZE: C SCALE: 7:1 SHEET 1 OF 1	
3 DECIMAL PLACES	±0.050	THIRD ANGLE PROJECTION				
ANGULAR DEGREES	±1°					